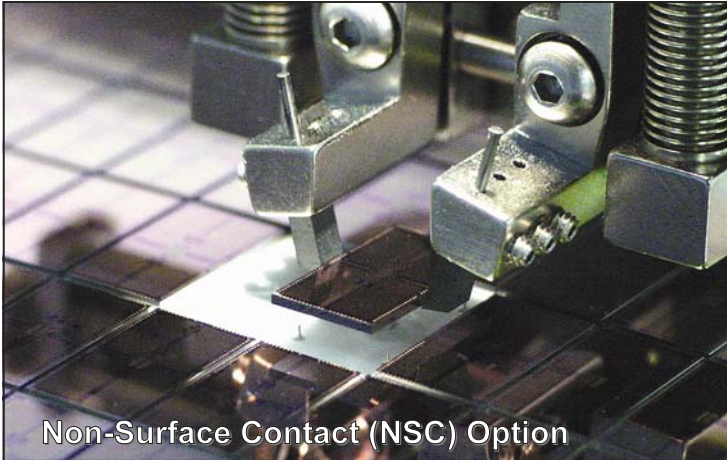


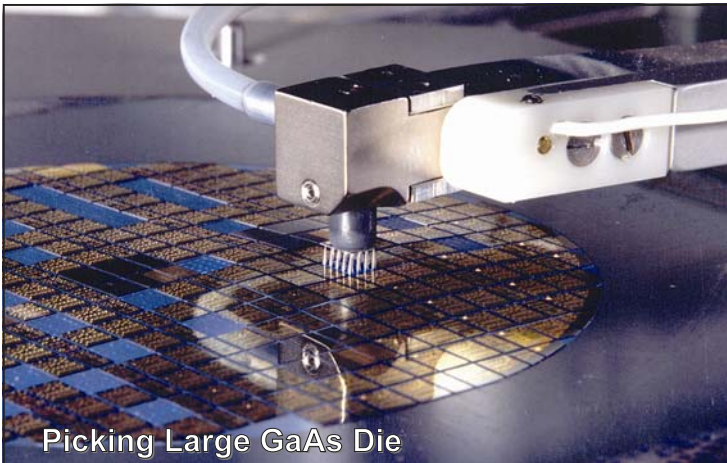
- Excels in sorting fragile GaAs and MEMS devices
- Available for up to 300mm wafers
- Picks die as small as 200 μm square
- Waffle pack, Gel-Pak[®] and film frame output
- Underside and facet inspection options
- Die inverter option
- Throughput of 500-1200 UPH, (product, process dependant)
- Quick change over, under 10 minutes
- Optional non-surface contact operation for MEMS, air-bridge GaAs, optical and other sensitive devices.



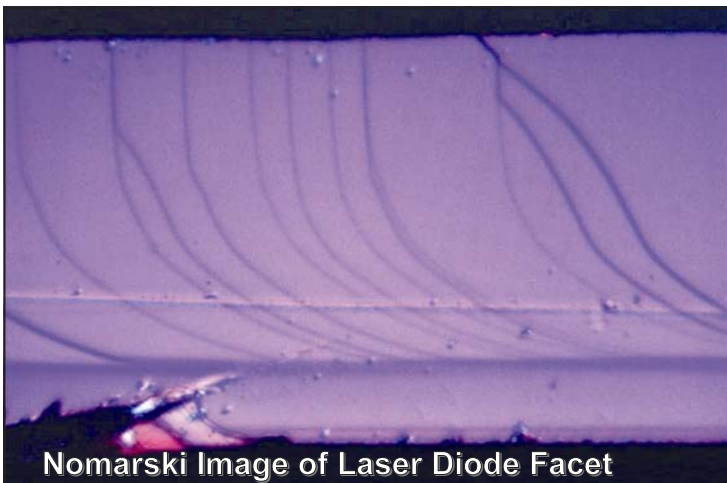
Die Inverter and Underside Inspect



Non-Surface Contact (NSC) Option



Picking Large GaAs Die



Nomarski Image of Laser Diode Facet

The System

The DE35-ST semi-automatic die pick and place system is an elegantly simple, low cost machine for picking die from sawn or scribed wafers mounted on adhesive film.

Die can be placed into waffle packs, Gel-Pak[®], film frame, or directly onto substrates.

Optimized for small lot production, the DE35-ST is simple to learn and use. No hand tools are needed for die size changeover. Setup and option information is preserved in user selectable recipes.

Hundreds of catalog waffle pack parameters are pre-programmed, with space for hundreds more user programmed parameters.

Waffle pack pockets for die placement are automatically selected. Manual selection using the keypad arrow keys enables completion of partially filled waffle packs.

Specifications

Smallest Die Size	200 μ m
Largest Die Size	>25mm
Largest Wafer	200mm, 300mm, special order
Die Placement	\pm 120 μ m
Die Surface Load	<10 gf
Throughput	500 to 1200 UPH

Dimensions

Weight	80 kg, 175 lbs
Width	1120 mm, 44 in.
Depth	840 mm, 33 in.
Height	660 mm, 26 in.

Utilities

Electrical	110-240 VAC 50-60 Hz, Single phase
Air	275 kPa to 550 kPa (40-80 psig)
Vacuum	-65 kPa (20in Hg)

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